



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



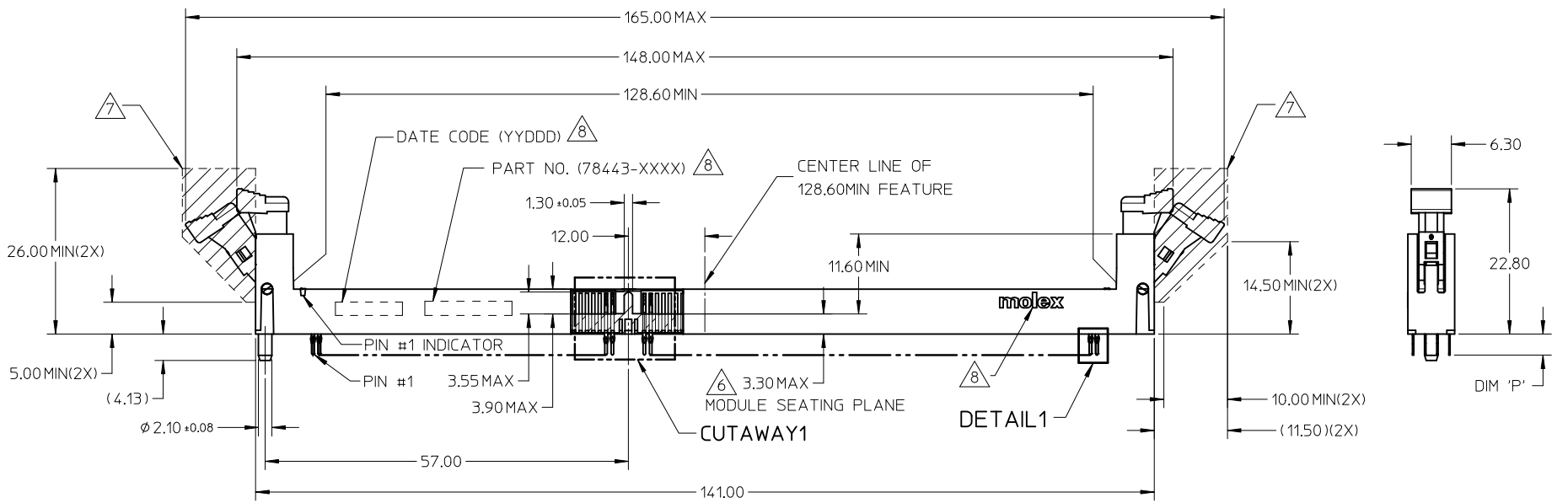
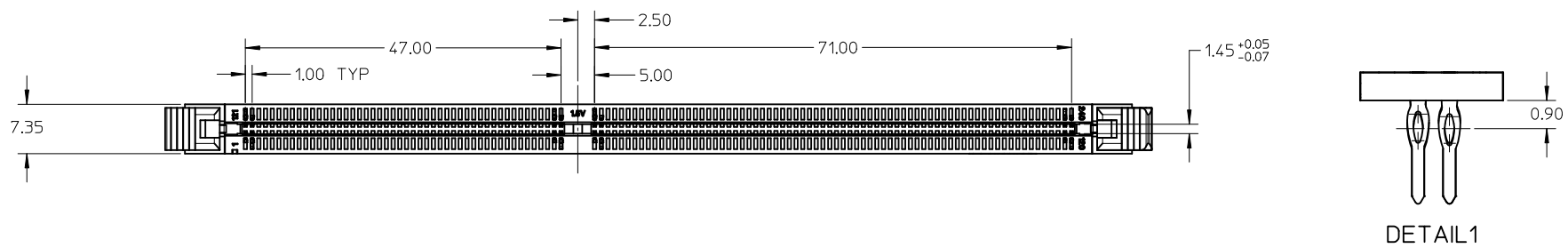
Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

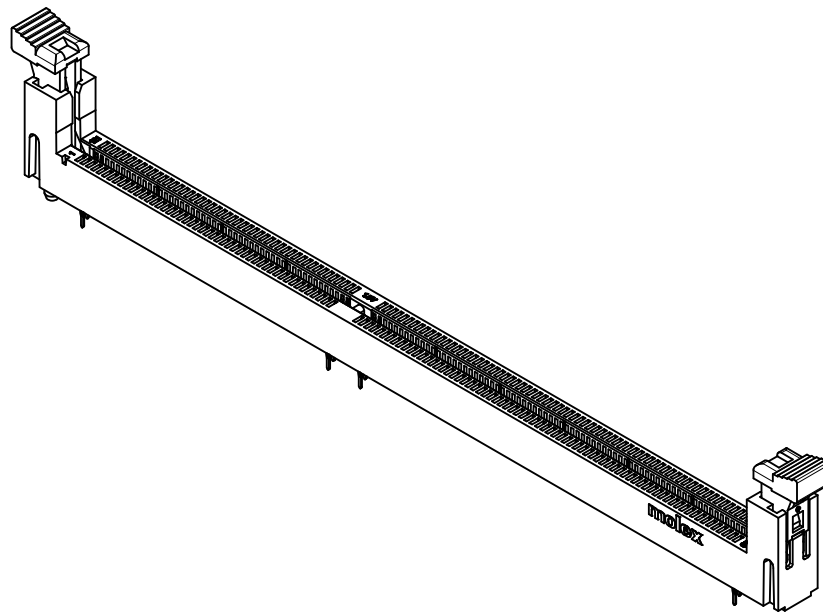
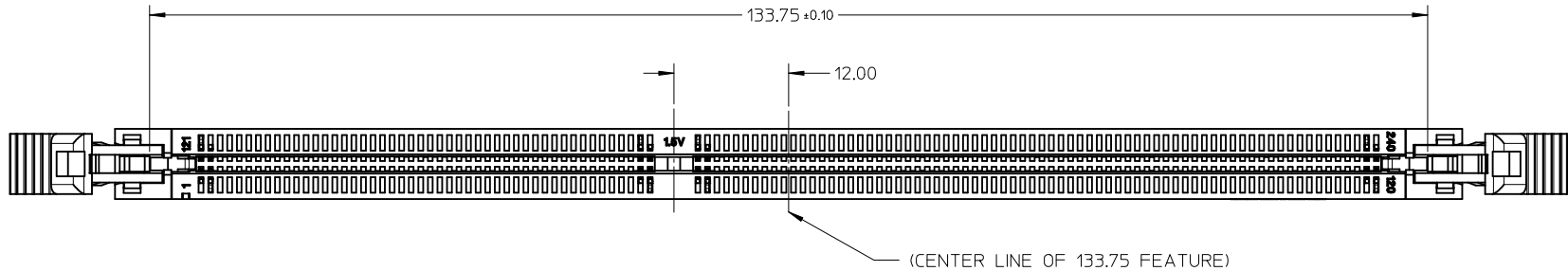




- NOTES:
- MATERIALS
HOUSING - HIGH TEMP NYLON GLASS FILLED, UL 94V-0, COLOUR - BLACK
LATCH - HIGH TEMP NYLON, COLOUR - BLACK
- POLYSULFONE, UL 94HB - CLEAR
TERMINAL - PHOSPHOR BRONZE
 - PLATING - SEE TABLE IN SHEET 4.
 - REFER TO PRODUCT SPEC. PS-78443-001 FOR PERFORMANCE SPECIFICATIONS.
 - PRODUCT SHALL BE PACKED IN TRAY.
 - CARD SLOT ACCEPTS 1.27±0.10MM MODULE THICKNESS. (MEASURED FROM P.C.PADS).
- 6 MODULE SEATING PLANE FROM TOP OF PCB.
 7 KEEP OUT ZONE RESERVED FOR LATCH.
 8 MOLEX LOGO, DATE & PART NO. INDICATED ON HOUSING.

FINAL RELEASE EC NO: S2010-0504 DRWN:CGTAN 2009/12/31 CHKD:CCTEH 2009/12/31 APPR:SHLENI 2009/12/31	DESCRIPTION QUALITY SYMBOLS $F_A=0$ $F_G=0$ $F_P=0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
				MM ONLY	NTS	METRIC		
		mm	INCH	DRAWN BY	DATE	TITLE		
		4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	CMTEO	2008/06/19	DDR3 DIMM, 100MM PITCH 240 CKTS, VERT PRESS-FIT LOW-LLCR		
		2 PLACES ± 0.2 ± ---	CHECKED BY	DATE	MOLEX MOLEX INCORPORATED			
		1 PLACE ± --- ± ---	CGTAN	2008/07/25				
		ANGULAR ± 1 °	APPROVED BY	DATE	MATERIAL NO.	DOCUMENT NO.	SHEET NO.	
			CGTAN	2008/07/25	SEE TABLE	SD-78443-001	1 OF 6	
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
			A3					

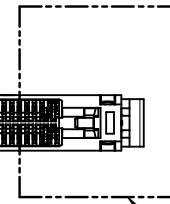
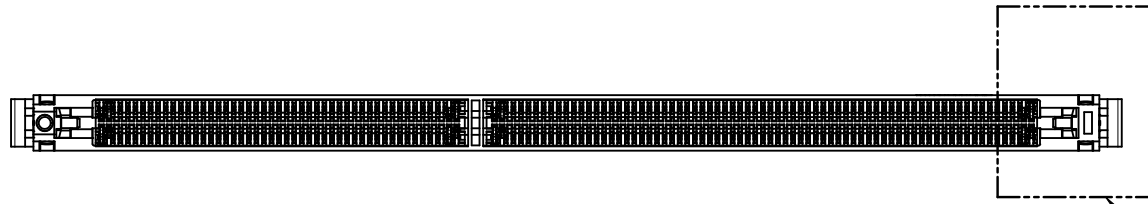
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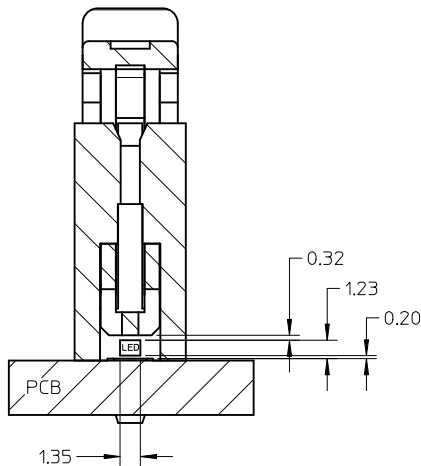
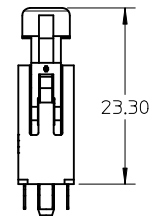
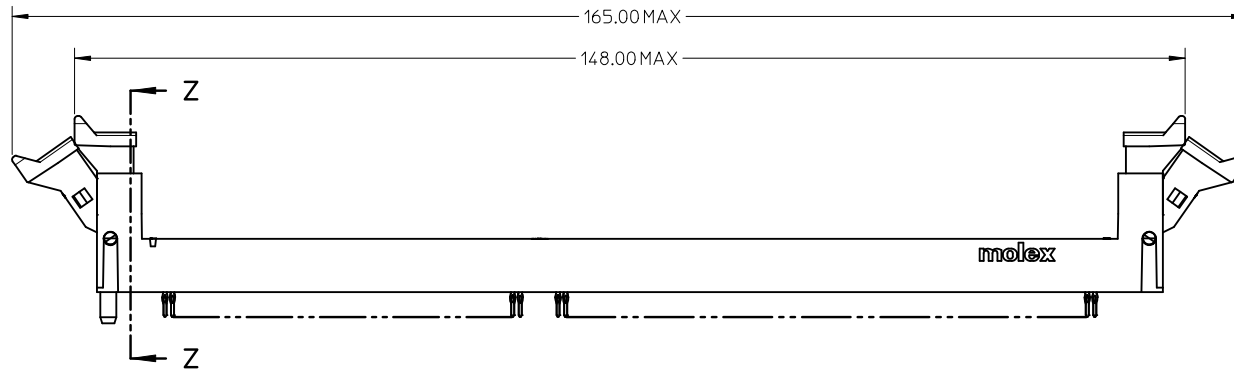
FINAL RELEASE EC NO: S2010-0504 DRWN:CGTAN 2009/12/31 CHKD:CCTEH 2009/12/31 APPR:SHLENI 2009/12/31	QUALITY SYMBOLS $\nabla_A = 0$ $\nabla_C = 0$ $\nabla_P = 0$	GENERAL TOLERANCES (UNLESS SPECIFIED) <table border="1"> <tr> <td></td> <td>mm</td> <td>INCH</td> </tr> <tr> <td>4 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>3 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>2 PLACES</td> <td>± 0.2</td> <td>± ---</td> </tr> <tr> <td>1 PLACE</td> <td>± ---</td> <td>± ---</td> </tr> </table>		mm	INCH	4 PLACES	± ---	± ---	3 PLACES	± ---	± ---	2 PLACES	± 0.2	± ---	1 PLACE	± ---	± ---	DIMENSION STYLE MM ONLY	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
		mm	INCH																		
	4 PLACES	± ---	± ---																		
	3 PLACES	± ---	± ---																		
2 PLACES	± 0.2	± ---																			
1 PLACE	± ---	± ---																			
DESCRIPTION DDR3 DIMM, 1.00MM PITCH 240 CKTS, VERT PRESS-FIT LOW-LLCR	DRAWN BY CMTEO	DATE 2008/06/19	TITLE DDR3 DIMM, 1.00MM PITCH 240 CKTS, VERT PRESS-FIT LOW-LLCR	CHECKED BY CGTAN	DATE 2008/07/25	APPROVED BY CGTAN	DATE 2008/07/25														
MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-78443-001	SHEET NO. 2 OF 6	MOLEX INCORPORATED	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION																	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS																				

9 8 7 6 5 4 3 2 1

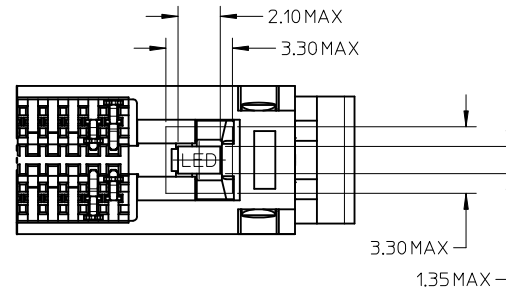
CONNECTOR WITH CLEAR LATCH



DETAIL2



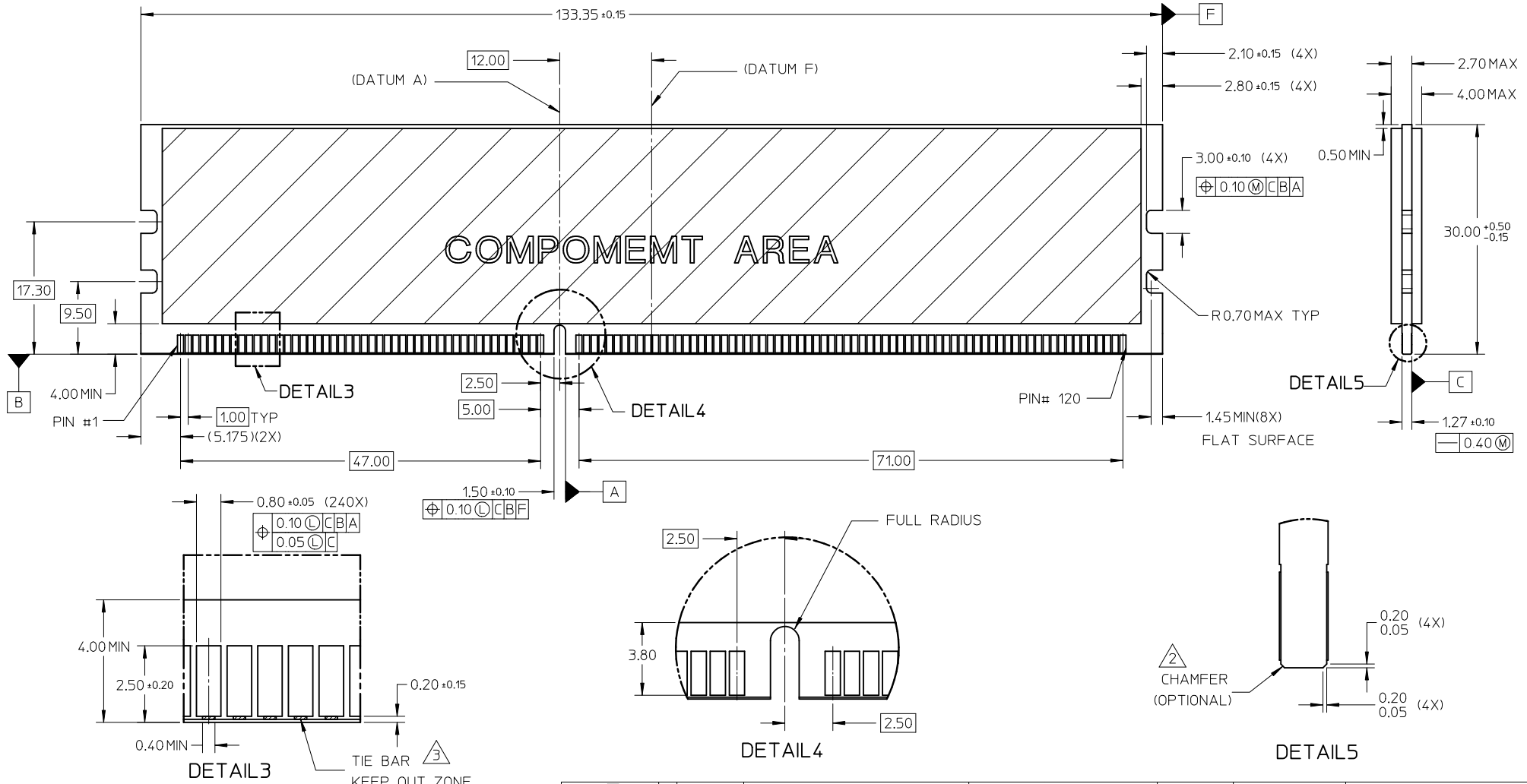
SECTION Z-Z



DETAIL2

FINAL RELEASE EC NO: S2010-0504 DRWN:CGTAN 2009/12/31 CHKD:CCTEH 2009/12/31 APPR:SHLENI 2009/12/31	QUALITY SYMBOLS $\nabla_A = 0$ $\nabla_C = 0$ $\nabla_P = 0$	GENERAL TOLERANCES (UNLESS SPECIFIED) mm INCH 4 PLACES \pm --- \pm --- 3 PLACES \pm --- \pm --- 2 PLACES ± 0.2 \pm --- 1 PLACE \pm --- \pm --- ANGULAR $\pm 1^\circ$	DIMENSION STYLE MM ONLY DRAWN BY: CMTEO CHECKED BY: CGTAN APPROVED BY: CGTAN DATE: 2008/06/19 DATE: 2008/07/25 DATE: 2008/07/25	SCALE NTS DESIGN UNITS METRIC THIRD ANGLE PROJECTION	TITLE DDR3 DIMM, 100MM PITCH 240 CKTS, VERT PRESS-FIT LOW-LLCR
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. SEE TABLE	DOCUMENT NO. MOLEX INCORPORATED SD-78443-001	SHEET NO. 3 OF 6	
	SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
	FINAL RELEASE EC NO: S2010-0504 DRWN:CGTAN 2009/12/31 CHKD:CCTEH 2009/12/31 APPR:SHLENI 2009/12/31				

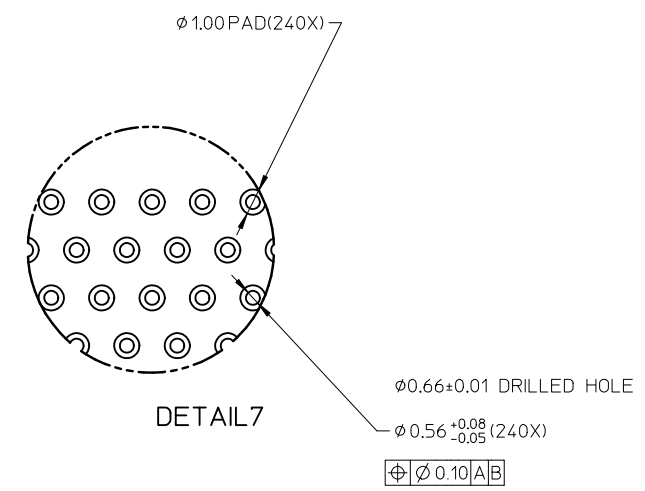
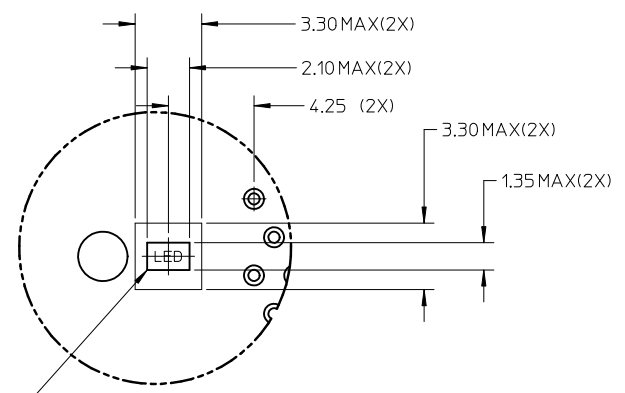
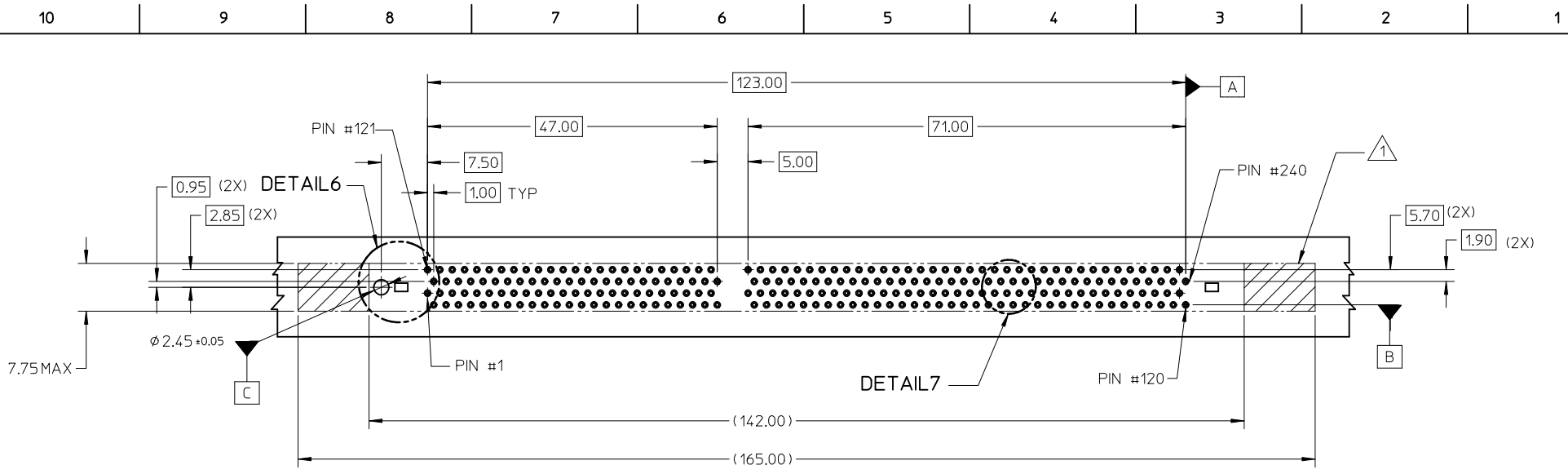
MODULE CARD
 DDR3 DUAL IN-LINE MEMORY MODULE FAMILY 1.00MM CONTACT CENTERS
 (JEDEC MO-269, ISSUE A, 12/05)



NOTES:

- RECOMMENDED PLATING FOR CONTACT PADS:
 PREFERRED: 0.76 MICROMETERS GOLD PLATING MIN OVER 2.00 MICROMETERS NICKEL
 ALTERNATIVE: 0.05-0.75 MICROMETERS GOLD PLATING OVER 2.00 MICROMETERS NICKEL MUST USE AN ELECTRONIC CONTACT GRADE CORROSIVE BARRIER LUBRICANT
- CHAMFER IS OPTIONAL AND IS NOT TO HIT THE GOLD PADS
- LEADING EDGE OF GOLD PADS SPECIFIED BY KEEPOUT ZONE SHALL BE FREE OF BURRS AND EXTERNAL TIE BARS.

FINAL RELEASE EC NO: S2010-0504 2009/12/31 DRWN:CGTAN CHKD:CCTEH APPR:SHLENI 2009/12/31	QUALITY SYMBOLS F _A =0 F _E =0 F _P =0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
		mm	INCH	MM ONLY	NTS	METRIC	⊙ □	
		4 PLACES	± ---	± ---	DRAWN BY	DATE	TITLE	
		3 PLACES	± ---	± ---	CMTEO	2008/06/19	DDR3 DIMM, 100MM PITCH 240 CKTS, VERT PRESS-FIT LOW-LLCR	
2 PLACES	± 0.2	± ---	CHECKED BY	DATE	MOLEX INCORPORATED		DOCUMENT NO.	
1 PLACE	± ---	± ---	CGTAN	2008/07/25	SD-78443-001		SHEET NO.	
ANGULAR ± 1 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY	DATE	4 OF 6		
MATERIAL NO.		SEE TABLE		CGTAN	2008/07/25	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
SIZE		A3						



'LED' IS FOR CLEAR LATCH VERION ONLY

DETAIL6

DETAIL7

NOTE:
 1 KEEP OUT AREA IS THE AREA WHERE THE CONNECTOR (INCLUDING LATCH) IS MOUNTED ON THE PCB.

FINAL RELEASE EC NO: S2010-0504 DRWN:CGTAN 2009/12/31 CHKD:CCTEH 2009/12/31 APPR:SHLENI 2009/12/31	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	$F_A=0$	mm	INCH	DRAWN BY CMTEO	DATE 2008/06/19	TITLE DDR3 DIMM, 100MM PITCH 240 CKTS, VERT PRESS-FIT LOW-LLCR			
	$F_C=0$	4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	CHECKED BY CGTAN	DATE 2008/07/25	MOLEX INCORPORATED			
	$F_P=0$	2 PLACES ± 0.2 ± ---	1 PLACE ± --- ± ---	APPROVED BY CGTAN	DATE 2008/07/25	DOCUMENT NO. SD-78443-001		SHEET NO. 5 OF 6	
	ANGULAR ± 1 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

TIN OPTION

PART NO.	VOLTAGE KEY POS.	VOLTAGE	DIM 'P'	RECOMMENDED PCB THICKNESS	CONTACT AREA PLATING OPTION	SOLDERTAIL PLATING OPTION	LATCH COLOUR
78443-0001	CENTER	1.5V	3.30±0.25	2.36	0.76 MICROMETER/ 30 MICROINCH MIN. GOLD OVER 1.27 MICROMETER/ 50 MICROINCH MIN NICKEL UNDERPLATE	0.38-1.52 MICROMETER/15-60 MICROINCH TIN OVER 1.27MICROMETER/ 50 MICROINCH MIN NICKEL UNDERPLATE	BLACK
78443-0005			3.30±0.25	2.36			CLEAR
78443-0051			2.55±0.15	2.36			BLACK
78443-0006			2.55±0.15	2.36			CLEAR

TIN/LEAD OPTION

PART NO.	VOLTAGE KEY POS.	VOLTAGE	DIM 'P'	RECOMMENDED PCB THICKNESS	CONTACT AREA PLATING OPTION	SOLDERTAIL PLATING OPTION	LATCH COLOUR
78443-0011	CENTER	1.5V	3.30±0.25	2.36	0.76 MICROMETER/ 30 MICROINCH MIN. GOLD OVER 1.27 MICROMETER/ 50 MICROINCH MIN NICKEL UNDERPLATE	0.38-1.52 MICROMETER/15-60 MICROINCH TIN/LEAD OVER 1.27MICROMETER/ 50 MICROINCH MIN NICKEL UNDERPLATE	BLACK
78443-0015			3.30±0.25	2.36			CLEAR
78443-0151			2.55±0.15	2.36			BLACK
78443-0016			2.55±0.15	2.36			CLEAR

FINAL RELEASE EC NO: S2010-0504 DRW:CGTAN 2009/12/31 CHKD:CCTEH 2009/12/31 APPR:SHLENI 2009/12/31 REV	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	$\nabla_A=0$ $\nabla_C=0$ $\nabla_P=0$	mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.2 ± --- 1 PLACE ± --- ± --- ANGULAR ± 1 °	MM ONLY	NTS	METRIC	
	DESCRIPTION	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DRAWN BY DATE CMTEO 2008/06/19 CHECKED BY DATE CGTAN 2008/07/25 APPROVED BY DATE CGTAN 2008/07/25	TITLE	DDR3 DIMM, 100MM PITCH 240 CKTS, VERT PRESS-FIT LOW-LLCR	
	A	SEE TABLE	MATERIAL NO. DOCUMENT NO.	MOLEX INCORPORATED	SD-78443-001	SHEET NO. 6 OF 6